



GE Energy

Functional Testing Specification

*Parts & Repair Operations
Louisville, KY*

LOU-GEF-IC600CM5xx

Test Procedure for Series Six CM type RPU Logic Memory cards

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1. SCOPE

1.1 This is a functional testing procedure for Series Six LX/LR memory cards.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires: broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors: broken or cracked

4.2.1.3 Components: visually damaged

4.2.1.4 Capacitors: bloated or leaking

4.2.1.5 Solder joints: damaged or cold

4.2.1.6 Circuit board: burned or de-laminated

4.2.1.7 Printed wire runs / Traces: burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1	H188896	RPU System
1	H033959	PDT

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6. Test Process

6.1 Setup

- 6.1.1** Ensure that the customer's card has a battery installed.
- 6.1.2** Measure the battery's voltage.
- 6.1.3** If the battery measures below 3.0VDC, replace it.
- 6.1.4** Turn off the power of RPU-1-Local-1.
- 6.1.5** Remove the shop Logic Memory card from slot # 7.
- 6.1.6** Install the customer's Logic Memory card into slot # 7.
- 6.1.7** Connect the data cable from the PDT to Port A of I/O control card.

6.2 Testing

- 6.2.1** Turn on the power of RPU-1-Local-1.
- 6.2.2** Turn on the PDT.
- 6.2.3** Follow the screen prompts to initiate auto testing.
- 6.2.4** Ensure that the processor column of the auto test screen continues to read "passed" as the auto test continues to scroll through the screen.
- 6.2.5** Allow this to continue for at least 15 minutes.
- 6.2.6** Turn off the PDT.
- 6.2.7** Turn off the power of RPU-1-Local-1.
- 6.2.8** Disconnect the data cable from Port A of the I/O control card.
- 6.2.9** Remove the customer's card.
- 6.2.10** Reinstall the shop card.

6.3 End of test.

7. NOTES

- 7.1** None at this time.

8. ATTACHMENTS

- 8.1** None at this time.